

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Withdrawn) A paste containing:

solids having a conductive substance and a resin; and

a solvent for dissolving the resin,

wherein a solids content of said paste is not less than 60 vol%.

2. (Withdrawn) A paste containing:

solids having a conductive substance and a resin; and

a solvent for dissolving the resin,

wherein a viscosity ratio of said paste is not more than 2.

3. (Withdrawn) A paste containing:

solids having a conductive substance and a resin; and

a solvent for dissolving the resin,

wherein a solids content of said paste is not less than 60 vol% and a viscosity ratio thereof is not more than 2.

4. (Cancelled)

5. (Withdrawn) A method of burying a paste in a trench formed in a major surface of a substrate, comprising:

forming said trench in said substrate; and  
burying, in said trench, a paste containing solids having a conductive substance and a resin, and a solvent for dissolving the resin, wherein a solids content of said paste is not less than 60 vol%.

6. (Withdrawn) A method of burying a paste in a trench formed in a major surface of a substrate, comprising:

forming said trench in said substrate; and  
burying, in said trench, a paste containing solids having a conductive substance and a resin; and a solvent for dissolving the resin, wherein a viscosity ration of said paste is not more than 2.

7. (Withdrawn) A method according to claim 5, wherein a viscosity ratio of said paste is not more than 2.

8. (Cancelled)

9. (Currently Amended) A method of burying powder in a trench having a bottom formed in a major surface of a substrate, comprising:

applying a dispersion of the powder in a solvent onto a region including the trench; [[and]]

precipitating the powder in the dispersion within the trench to bury the trench with the precipitated powder; and

polishing a lower surface of the substrate to expose the powder buried in said trench.

10. (Previously presented) A method according to claim 9, wherein the dispersion contains a resin.

11. (Original) A method according to claim 9, wherein a portion of said powder is a glass powder.

12. (Original) A method according to claim 10, wherein a portion of said powder is a glass powder.

13-24. (Cancelled)

25. (Withdrawn) A method according to claim 5, further comprising polishing a lower surface of the substrate to expose the paste buried in said trench.

26. (Withdrawn) A method according to claim 5,  
wherein said forming the trench includes forming a plug hole in an upper surface of said substrate, and said burying includes burying said paste into said plug hole; and  
wherein said method further comprises:  
removing the lower surface of the substrate until the paste buried at a bottom portion of said plug hole appears to form a chip-through plug.

27. (Withdrawn) A method according to claim 6, further comprising polishing a lower surface of the substrate to expose the paste buried in said trench.

28. (Withdrawn) A method according to claim 6,  
wherein said forming the trench includes forming a plug hole in an upper surface of said substrate, and said burying includes burying said paste into said plug hole, and wherein said method further comprises:

removing the lower surface of the substrate until the paste buried at a bottom portion of said plug hole appears to form a chip-through plug.

29. (Canceled)

30. (Currently Amended) A method according to claim 9, of burying powder in a trench having a bottom formed in a major surface of a substrate, comprising:  
applying a dispersion of the powder in a solvent onto a region including the trench;

precipitating the powder in the dispersion within the trench to bury the trench with the precipitated powder,

wherein the trench includes a plug hole having a bottom formed in an upper surface of said substrate, and said precipitating includes precipitating said powder within said plug hole; and

wherein said method further comprises: comprising removing the lower surface of the substrate until the powder buried at a bottom portion of said plug hole appears to form a chip-through plug.